Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1-16 (canceled)
- 17. (currently amended) A surface treatment process, comprising: providing a hydrophillic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TMAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns.
- 18. (original) The process described in claim 17 wherein the TMAH has a concentration in said deionized water of between about 2% and 20%.
- 19. (original) The process described in claim 17 wherein said abrasive particles are selected from the group consisting of alumina and silica.
 - 20. (canceled)
- 21. (original) The process described in claim 17 wherein said hydrophilic surface is selected from the group consisting of tungsten, silicon oxide, and copper.
- 22. (currently amended) A surface treatment process, comprising: providing a hydrophillic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TBAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns.
- 23. (original) The process described in claim 22 wherein the TBAH has a concentration in said deionized water of between about 2 and 20%.

Appl. No. 10/696,432 Reply to Office Action of December 28, 2004

- 24. (original) The process described in claim 22 wherein said abrasive particles are selected from the group consisting of alumina and silica.
 - 25. (canceled)
- 26. (original) The process described in claim 22 wherein said hydrophilic surface is selected from the group consisting of tungsten, silicon oxide, and copper.
 - 27-30 (canceled)